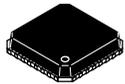


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

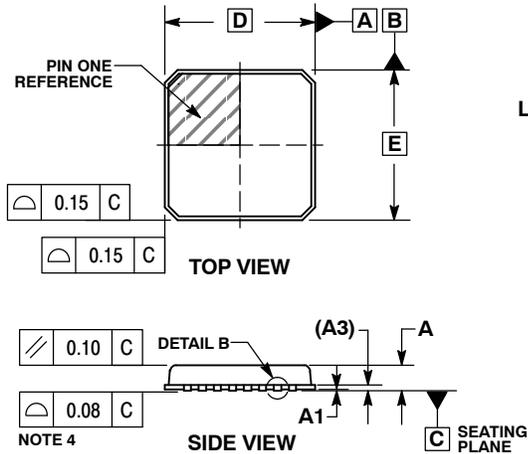
ON Semiconductor®



SCALE 2:1

QFN32 5x5, 0.5P (PUNCHED)
CASE 485CZ
ISSUE A

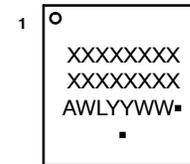
DATE 29 JUL 2013



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSIONS: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	0.90
A1	---	0.05
A3	0.20	REF
b	0.20	0.30
D	5.00	BSC
D2	3.20	3.40
E	5.00	BSC
E2	3.20	3.40
e	0.50	BSC
L	0.30	0.50

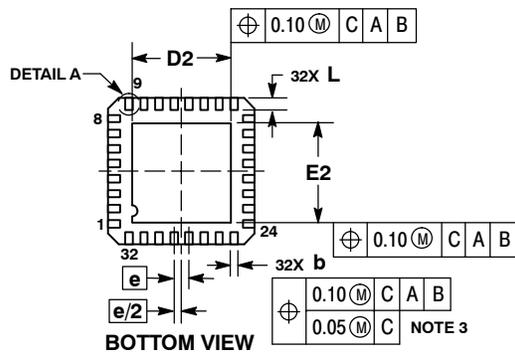
GENERIC MARKING DIAGRAM*



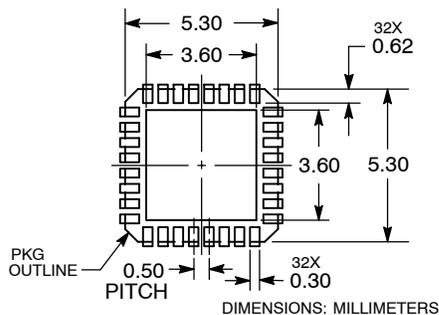
- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



RECOMMENDED SOLDERING FOOTPRINT



DOCUMENT NUMBER:	98AON87072E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN32 5x5, 0.5P (PUNCHED)	PAGE 1 OF 2

